

**AMENDMENTS TO THE SPECIFICATION**

Please replace the Abstract on page 16 with the following rewritten Abstract:

A semiconductor chip package includes an IC chip and a tape circuit substrate. The tape circuit substrate has a base film and a plurality of beam leads formed on the base film. One end portion of each beam lead extends from the base film, and the extended portion has a widthwise wavy portion. The widthwise wavy portion ~~can~~may be, for example, semicircular shaped, an S-shaped, or a zig-zag shaped. The IC chip has chip pads formed on a top surface thereof. ~~The beam lead is bonded to the chip pad through an inner lead bonding (ILB) process. During the ILB process, the wavy portion disperses the stress produced in the beam lead. Therefore, a crack or a break of the beam lead due to the stress can be effectively prevented, improving interconnection reliability between the IC chip and the tape circuit substrate.~~